

Singulation System

Model LGR1040



Half-cut machine suitable for wettable QFN packages



English

Half-cut machine suitable for wettable QFN packages

- Enables high-precision blade cutting. of lead-less device products such as QFN packages.
- Selectable blade cut (FMS3040-HC) or laser cut (LGR1040) depending on process and lead frame design.
- Combining dedicated lead frames with lasers to ensure stable groove depth.



SPECIFICATION

Items		Unit	Description		
Model		—	LGR1040		
Workpiece size	Length	mm	240—300		
	Width	mm	74—100		
	Thickness	mm	0.6—2.0		
Package size	Min.	mm	1×1		
	Max.	mm	40×40 (Scan FOV)		
Warpage amount of substrate		—	4mm/300mm (Max.)		
Laser		—	1 Head, Single table		
External dimensions	Module	module	Loader	Cut Engine	Unloader
	Width	mm	950	700	850
	Depth	mm	900	1,700	900
	Height	mm	1,700	1,700	1,700
Weight		ton	1.5		
Onload	Type	—	Slit magazine		
	Pieces	pcs	4 (Max.) In case substrate width is 115mm		
Offload	Type	—	Slit magazine		
	Pieces	pcs	4 (Max.) In case substrate width is 115mm		
Conversion time		min	20		
Package handling method		—	Vacuum		
Machine capacity		UPH	4,600 at QFN4×4 (672 packages/workpiece)		

- The figures shown above are based on standard machine specifications.
- The above specification are subject to change without prior notice.
- For special requirements, please consult your local TOWA representative.



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